

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Withdrawn) A hybrid integrated circuit provided with:
a chip component with terminal electrodes formed at both ends, conductive wiring layers in which plurality of pads are provided in a manner corresponding to the terminal electrodes, an overcoat resin for covering the conductive wiring layers excluding the pads, and external electrodes which are electrically connected to the conductive wiring layers, wherein
a space portion is provided in the overcoat resin between the pads where the terminal electrodes of the chip component are attached by a brazing material.
2. (Withdrawn) A hybrid integrated circuit provided with:
a chip component with terminal electrodes formed at both ends, conductive wiring layers in which plurality of pads are provided in a manner corresponding to the terminal electrodes, an overcoat resin for covering the conductive wiring layers excluding the pads, and external electrodes made of a brazing material so as to be electrically connected to the conductive wiring layers , wherein
an insulating resin is provided between the pads where the terminal electrodes of the chip component are attached by a brazing material.
3. (Withdrawn) The hybrid integrated circuit of Claim 2, wherein
as the insulating resin between the pads, an underfill resin is used.
4. (Currently Amended) A hybrid integrated circuit provided with:

a chip component with terminal electrodes ~~formed~~ at both ends;[[,]]
conductive wiring layers in which a plurality of pads are provided in a manner
corresponding to the terminal electrodes;[[,]]
an overcoat resin for covering the conductive wiring layers excluding the pads;[[,]]
~~and the~~ external electrodes comprising ~~made of~~ a brazing material so as to be electrically
connected to the conductive wiring layers;~~wherein~~
a plating on ~~containing no tin is applied to~~ the terminal electrodes of the chip component,
wherein the plating does not contain tin; and
a brazing material to adhere the terminal electrodes to the pads, ~~is a~~ wherein the brazing
material has ~~with~~ a higher melting point than that of a brazing material of ~~to form~~ the external
electrodes.

5. (Withdrawn) A hybrid integrated circuit comprising:

a chip component with a terminal electrodes formed at both ends, conductive wiring
layers in which plurality of pads are provided in a manner corresponding to the terminal
electrodes, and an overcoat resin for covering the conductive wiring layers excluding the pads,
wherein

a conductive adhesive is provided on the pads, an insulating adhesive is provided
between the pads, the chip component body is adhered to the overcoat resin by the insulating
adhesive, and the terminal electrodes of the chip component are adhered to the pads by the
conductive adhesive.

6. (Withdrawn) The hybrid integrated circuit of Claim 5, wherein

the insulating adhesive is disposed at a height to make contact with the chip component
body in advance of the conductive adhesive.

7. (New) The hybrid integrated circuit of Claim 4 comprising a space in the overcoat resin between the pads where the terminal electrodes of the chip component are adhered by the brazing material.

8. (New) The hybrid integrated circuit of Claim 4 comprising an insulating resin between the pads where the terminal electrodes of the chip component are adhered by the brazing material.

9. (New) The hybrid integrated circuit of Claim 8 wherein the insulating resin between the pads is an underfill resin.